

Via Facsimile (703) 872-9306Serial No. 10/689,936
11Z.003D2C

Amendment Under 37 C.F.R. 1.312 dated July 1, 2005

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**In re PATENT APPLICATION of****Takashi Ohsumi**

Group Art Unit: 2823

**RECEIVED
CENTRAL FAX CENTER****Serial No.: 10/689,936**

Examiner: F. Toledo

JUL 01 2005**Filed: October 22, 2003**

Confirm. No.: 4027

**For: METHOD FOR FABRICATING A SEMICONDUCTOR APPARATUS
INCLUDING A SEALING MEMBER WITH REDUCED THERMAL STRESS****AMENDMENT UNDER 37 C.F.R. 1.312**

U.S. Patent and Trademark Office
Customer Window, Mail Stop Issue Fee
Randolph Building
401 Dulany Street
Alexandria, VA 22314

Date: July 1, 2005

*Please enter
7/20/05
LLJ.***Sir:**

Responsive to the Notice of Allowance dated June 15, 2005, the following amendments and remarks are respectfully submitted in connection with the above-identified application under 37 C.F.R. 1.312.

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 4 of this paper.

Page 1 of 4